

FORECAST CHANGE NOTIFICATION

MLP 5x6 Discrete Cu Wire Conversion

This is to inform you that a design and/or process change will be made to the following product(s). This notification is for your information and concurrence. This is a preliminary notification. A Final PCN will be issued when qualification is complete and data is available.

If you require data or samples to qualify this change, please contact **Fairchild Semiconductor within 30 days of receipt of this notification.**

If you have any questions concerning this change, please contact:

Technical Contact:

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Phone: 604-6437211 ext 685

PCN Originator:

Name: Ti, CS  
E-mail: CS.Ti@fairchildsemi.com  
Phone: 604-6437211 ext 685

Implementation of change:

Expected 1st Device Shipment Date: 2007/06/01

Earliest Year/Work Week of Changed Product: H2

Change Type Description: Bond Wire Material Composition

Description of Change (From): Wire bond material currently used for our MLP 5x6 discrete products assembled from Fairchild (M), FSPm facility will be changed from Au wire to Cu wire. Package with this change will have an identifier. There will be no change in terms of wire diameter and type of thermosonic bonding process applied.

Description of Change (To): From Au wire used in MLP 5x6 Discrete products to Cu wire

Reason for Change : Change from Au wire to Cu wire is to enhance RDSon performance. Cu wire use in place of Au will result in lower RDSon. There will be no adverse impact on products' quality and reliability. Products will be assembled at the same quality level as before.

Qual/REL Plan Numbers : Q20060405

Qualification Plan covers all biased and non-biased stresses and assembly level reliability data (wire pull, ball shear, bond and weld formations, craters). Please refer to qualification plan attached for details.

Qualification :

Qualification Plan covers all biased and non-biased stresses and assembly level reliability data (wire pull, ball shear, bond and weld formations, craters). Please refer to qualification plan attached for details.

Qualification Stress Test and Sample Size Detail

Device #1	FDMS2572
Package:	-1
#Leads:	-1

Precondition Description:

				Readpoints		Sample	
Stress	P/C	Standard	Conditions			A	
PCNL1A		JESD22-A113				0	

Environment Stress Detail:

				Readpoints			Samples
Stress	P/C	Standard	Conditions	TP1	TP2	TP3	A
ACLV	X	JESD22-A102	100%RH, 121C	96			79
HAST1	X	JESD22-A110	85%RH, 130C, 0V	96			79
HTGB		JESD22-A108	150C, 0V	168	500	1000	79
HTRB		JESD22-A108	150C, 0V	168	500	1000	79
HTSL		JESD22-A103	150C	168	500	1000	79
PRCL		MIL-STD-750-1036	Delta 100CC, 2 Min cycle	5000	10000		79
TMCL1	X	JESD22-A104	-65C, 150C	100	500		79

Device #2	FDMS8690
Package:	
#Leads:	

Precondition Description:

				Readpoints				Sample			
Stress	P/C	Standard	Conditions					A	B	C	D
PCNL1A		JESD22-A113						0	0	0	0

Environment Stress Detail:

				Readpoints			Samples			
Stress	P/C	Standard	Conditions	TP1	TP2	TP3	A	B	C	D
ACLV	X	JESD22-A102	100%RH, 121C	96			79	79	79	79
HAST1	X	JESD22-A110	85%RH, 130C, 0V	96			79	79	79	79
HTGB		JESD22-A108	150C, 0V	168	500	1000	79	79	79	79
HTRB		JESD22-A108	150C, 0V	168	500	1000	79	79	79	79
HTSL		JESD22-A103	150C	168	500	1000	79	79	79	79
PRCL		MIL-STD-750-1036	Delta 100CC, 2 Min cycle	5000	10000		79	79	79	79
TMCL1	X	JESD22-A104	-65C, 150C	100	500		79	79	79	79

Product Id Description : This change will affect certain products currently assembled in our MLP 5x6 packages from Fairchild (M), FSPM. Products affected by this change are listed in the Affected FSID List attached.

Affected FSIDs :

FDMS2572	FDMS3572	FDMS3672
FDMS8690		